SN54LV08A ... J OR W PACKAGE

SN74LV08A . . . D, DB, DGV, NS, OR PW PACKAGE

(TOP VIEW)

1A [

SCLS387D - SEPTEMBER 1997 - REVISED MAY 2000

- *EPIC* [™] (Enhanced-Performance Implanted CMOS) Process
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- 2-V to 5.5-V V_{CC} Operation
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Small-Outline (D, NS), Shrink Small-Outline (DB), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages, Ceramic Flat (W) Packages, Chip Carriers (FK), and DIPs (J)

description

These quadruple 2-input positive-AND gates are designed for 2-V to 5.5-V V_{CC} operation.

The 'LV08A devices perform the Boolean function

 $Y = A \bullet B$ or $Y = \overline{A + B}$ in positive logic.

The SN54LV08A is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74LV08A is characterized for operation from -40° C to 85°C.

10	(each g	
INP	UTS	OUTPUT
Α	В	Y
Н	Н	Н
L	Х	L
Х	L	L

FUNCTION TABLE



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



1B [] 2 13]] 4B 1Y [] 3 12 [] 4A

14 VCC

2A [4 2B [5	11] 4Y 10] 3B 9] 3A 8] 3Y
2B 🛿 5	10 🛛 3B
2Y 🛛 6	9 🛛 3A
GND 🛛 7	8 3Y

SN54LV08A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

SCLS387D - SEPTEMBER 1997 - REVISED MAY 2000

logic symbol[†]



 \dagger This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Voltage range applied to any output in the hig	Ih-impedance	
or power-off state, V _O (see Note 1)		–0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2		
Input clamp current, I _{IK} (V _I < 0)		
Output clamp current, I_{OK} (V _O < 0 or V _O > V _O		
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$		
Continuous current through V _{CC} or GND		
Package thermal impedance, θ_{JA} (see Note 3		
	DB package	
	DGV package	127°C/W
	NS package	
	PW package	113°C/W
Storage temperature range, T _{stg}		

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 5.5 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51.



SCLS387D - SEPTEMBER 1997 - REVISED MAY 2000

			SN54	LV08A	SN74I	_V08A	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
\ <i>\</i>	ligh lovel input veltage	V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
VIH	High-level input voltage	V _{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
VIL		V _{CC} = 2.3 V to 2.7 V		$V_{CC} imes 0.3$		$V_{CC} \times 0.3$	v
	Low-level input voltage	V _{CC} = 3 V to 3.6 V		V _{CC} × 0.3		$V_{CC} \times 0.3$	v
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
VI	Input voltage		0	5.5	0	5.5	V
Vo	Output voltage		0	✓ V _{CC}	0	VCC	V
		$V_{CC} = 2 V$	5	-50		-50	μA
1	Lligh lovel output output	V _{CC} = 2.3 V to 2.7 V	00	-2		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V	4	-6		-6	mA
		V _{CC} = 4.5 V to 5.5 V		-12		-12	
		$V_{CC} = 2 V$		50		50	μA
1		V _{CC} = 2.3 V to 2.7 V		2		2	
IOL	Low-level output current	V _{CC} = 3 V to 3.6 V		6		6	mA
		V _{CC} = 4.5 V to 5.5 V		12		12	
		V_{CC} = 2.3 V to 2.7 V	0	200	0	200	
$\Delta t/\Delta v$	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V	0	100	0	100	ns/V
		V _{CC} = 4.5 V to 5.5 V	0	20	0	20	
TA	Operating free-air temperature		-55	125	-40	85	°C

recommended operating conditions (see Note 4)

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN5	4LV08A		SN7	4LV08A		UNIT
PARAMETER	TEST CONDITIONS	v _{cc}	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
Vou	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V
VOH	I _{OH} = -6 mA	3 V	2.48			2.48			v
	I _{OH} = -12 mA	4.5 V	3.8	M		3.8			
	I _{OL} = 50 μA	2 V to 5.5 V		Ņ	0.1			0.1	
Ve	I _{OL} = 2 mA	2.3 V		24	0.4			0.4	V
VOL	I _{OL} = 6 mA	3 V	ć	1	0.44			0.44	v
	I _{OL} = 12 mA	4.5 V	ng		0.55			0.55	
Ц	$V_{I} = V_{CC}$ or GND	0 V to 5.5 V	04		±1			±1	μΑ
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V	Q.		20			20	μΑ
loff	$V_I \text{ or } V_O = 0 \text{ to } 5.5 \text{ V}$	0 V			5			5	μΑ
Ci	V _I = V _{CC} or GND	3.3 V		3.3			3.3		рF
		5 V		3.3			3.3		μ

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCLS387D - SEPTEMBER 1997 - REVISED MAY 2000

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETED	ARAMETER FROM TO L		LOAD	Т	ן = 25°C	;	SN54LV08A	SN74L	.V08A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MIN	MAX	UNIT
^t pd	A or B	Y	C _L = 15 pF		7.9*	13.8*	17*	1	16	ns
^t pd	A or B	Y	C _L = 50 pF		10.5	17.3	1 21	1	20	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	ARAMETER FROM TO LOAD		Т,	₄ = 25°C	;	SN54LV08	BA	SN74L	V08A	UNIT	
FARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	AX	MIN	MAX	UNIT
^t pd	A or B	Y	C _L = 15 pF		5.6*	8.8*	0* 11	1.5*	1	10.5	ns
^t pd	A or B	Y	C _L = 50 pF		7.5	12.3	৾৾ঀ৾	15	1	14	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	AMETER FROM TO LOAD		Т	ן = 25°C	;	SN54LV0	8A	SN74L	V08A	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MINS	MAX	MIN	MAX	UNIT
^t pd	A or B	Y	C _L = 15 pF		4.1*	5.9*		8*	1	7	ns
^t pd	A or B	Y	C _L = 50 pF		5.5	7.9		10	1	9	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

	PARAMETER				
		MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
VOL(V)	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}		3.1		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

I		PARAMETER	TEST CO	V _{CC}	TYP	UNIT	
	Card	Power dissipation capacitance	$C_{1} = 50 \text{pF},$	f = 10 MHz	3.3 V	8	рF
	Cpd		0 <u> </u>	1 - 10 10112	5 V	10	р

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCLS387D - SEPTEMBER 1997 - REVISED MAY 2000



PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as t_{dis}.
- F. tpzL and tpzH are the same as t_{en} .
- G. tpHL and tpLH are the same as t_{pd} .
 - PHL and tPLH are the same as tpg.

Figure 1. Load Circuit and Voltage Waveforms



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 2000, Texas Instruments Incorporated